RELIABILITY REPORT
FOR
MAX4173HEUT+T
PLASTIC ENCAPSULATED DEVICES

January 23, 2012

MAXIM INTEGRATED PRODUCTS
120 SAN GABRIEL DR.
SUNNYVALE, CA 94086

Approved by
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Conclusion

The MAX4173HEUT+T successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX4173 low-cost, precision, high-side current-sense amplifier is available in a tiny SOT23-6 package. It features a voltage output that eliminates the need for gain-setting resistors and it is ideal for today's notebook computers, cell phones, and other systems where current monitoring is critical. High-side current monitoring is especially useful in battery-powered systems, since it does not interfere with the ground path of the battery charger. The input common-mode range of 0 to +28V is independent of the supply voltage and ensures that the current-sense feedback remains viable even when connected to a battery in deep discharge. The MAX4173's wide 1.7MHz bandwidth makes it suitable for use inside battery charger control loops. The combination of three gain versions and a user-selectable external sense resistor sets the full-scale current reading. This feature offers a high level of integration, resulting in a simple and compact current-sense solution. The MAX4173 operates from a single +3V to +28V supply, typically draws only 420µA of supply current over the extended operating temperature range (-40°C to +85°C), and is offered in the space-saving SOT23 package.

II. Manufacturing Information

A. Description/Function:	Low-Cost, SOT23, Voltage-Output, High-Side Current-Sense Amplifier
B. Process:	S12
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Thailand
F. Date of Initial Production:	January 23, 1999

III. Packaging Information

A. Package Type:	6L SOT23
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-3001-0135 / A
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	1
J. Single Layer Theta Ja:	N/A
K. Single Layer Theta Jc:	80°C/W
L. Multi Layer Theta Ja:	230°C/W
M. Multi Layer Theta Jc:	76°C/W

IV. Die Information

A. Dimensions:	44 X 38 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	1.2 microns (as drawn)
F. Minimum Metal Spacing:	1.2 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Richard Aburano (Manager, Reliability Engineering) Don Lipps (Manager, Reliability Engineering) Bryan Preeshl (Vice President of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 160 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 6.9 \times 10^{-9}$

λ = 6.9 F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maxim-ic.com/qa/reliability/monitor. Cumulative monitor data for the S12 Process results in a FIT Rate of 0.17 @ 25C and 3.00 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing (lot NV9ACA440A)

The OP81-2 die type has been found to have all pins able to withstand a HBM transient pulse of +/-4000V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250mA.

Table 1
Reliability Evaluation Test Results

MAX4173HEUT+T

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)					
	Ta = 135°C	DC Parameters	80	0	IV9BBQ003B, D/C N/A
	Biased	& functionality	80	0	NV9AAX001E, D/C N/A
	Time = 192 hrs.				

Note 1: Life Test Data may represent plastic DIP qualification lots.